



Material Content Data Sheet



Sales Product Name	1EBN1001AE			Issued		11. December 2019		
MA#	MA005410448							
Package	PG-DSO-14-43			Weight*		149.24 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.321	2.23	2.23	22252	22252
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		117	
	non noble metal	zinc	7440-66-6	0.070	0.05		466	
	non noble metal	iron	7439-89-6	1.392	0.93		9326	
	non noble metal	copper	7440-50-8	56.512	37.87	38.86	378673	388582
wire	non noble metal	copper	7440-50-8	0.225	0.15	0.15	1511	1511
encapsulation	organic material	carbon black	1333-86-4	0.168	0.11		1127	
	plastics	epoxy resin	-	7.740	5.19		51861	
	inorganic material	silicondioxide	60676-86-0	76.218	51.06	56.36	510717	563705
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8216	8216
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9498	9498
glue	plastics	epoxy resin	-	0.233	0.16		1559	
	noble metal	silver	7440-22-4	0.698	0.47	0.63	4677	6236
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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